Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2043	@ad<="20040301" and (257/717-718).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:27
L2	1319	@ad<="20040301" and (257/706).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:09
L3	714	@ad<="20040301" and (257/720).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:10
L4	812	@ad<="20040301" and (257/675).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:11
L5	147	@ad<="20040301" and (257/625).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:10
L6	163	@ad<="20040301" and (257/276).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:33
L7	625	@ad<="20040301" and (438/122).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:10
L8	1452	@ad<="20040301" and (174/16.3).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:10
L9	176	@ad<="20040301" and (228/222).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:11
L10	18	@ad<="20040301" and (361/274.3).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:11
L11	767	@ad<="20040301" and (361/697).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:07

L12	341	@ad<="20040301" and (361/702). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:11
L13	671	@ad<="20040301" and (361/709). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:12
L14	11	@ad<="20040301" and (361/514). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:12
L17	439	@ad<="20040301" and 'thermal' with 'electrical' and 'semiconductor body'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:35
L18	16	@ad<="20040301" and 'thermal' with 'electrical' and 'semiconductor body' and 'trough'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:36
L19	0	@ad<="20040301" and 'heat sink' same ('SiC' or 'diamond') and 'semiconductor body' and 'trough'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:37
L20	28	@ad<="20040301" and 'heat sink' same ('SiC' or 'diamond') and 'semiconductor body'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:45
L21	169	@ad<="20040301" and 'thermo-electrical'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:50
L22	22	@ad<="20040301" and 'thermo-electrical' and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:05
L23	0	@ad<="20040301" and 'semiconductor boby' and 'heat sink' and 'conductive' and 'heat transfer' same 'helix'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:08
L24	0	@ad<="20040301" and 'semiconductor boby' and 'heat sink' and 'conductive' and 'heat transfer' same 'maze'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:07

L25	0	@ad<="20040301" and 'semiconductor boby' and 'heat sink' and 'conductive' and 'heat transfer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:07
L26	0	@ad<="20040301" and 'semiconductor boby' and 'heat sink' and 'conductive'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:07
L28	5	@ad<="20040301" and 'semiconductor' and 'heat sink' and 'conductive' and 'heat transfer' same 'helix'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:09
L29	7	@ad<="20040301" and 'semiconductor' and 'heat sink' and 'conductive' and 'heat transfer' same 'maze'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:11
L30	4	@ad<="20040301" and 'heat regulating' and 'semiconductor' and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:17
L31	0	@ad<="20040301" and 'heat regulating device' and 'IC' and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:17
L32	0	@ad<="20040301" and 'heat regulating' and 'IC' and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:18
L33	7	@ad<="20040301" and 'heat regulating' and 'chip' and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:19
L34	0	@ad<="20040301" and 'heat regulating device' same 'maze'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:20
L35	0	@ad<="20040301" and 'heat regulating device' same 'helix'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:44
L36	55	@ad<="20040301" and 'heat sink' same 'helix'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:25

L37	8	@ad<="20040301" and 'heat sink' same 'maze'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:32
L38	9	@ad<="20040301" and 'heat sink' same 'helix' and 'semiconductor'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:25
L39	0	@ad<="20040301" and 'thermal' with 'regulating' same 'semiconducotr' same ('heat sink' or 'heat spreader')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:46
L40	0	@ad<="20040301" and 'thermal' with 'control' same 'semiconducotr' same ('heat sink' or 'heat spreader')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:46
L41	0	@ad<="20040301" and 'heat' with 'control' same 'semiconducotr' same ('heat sink' or 'heat spreader')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:46
L42	4	@ad<="20040301" and 'thermal' with 'regulating' same 'semiconductor' same ('heat sink' or 'heat spreader')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:46
L43	737	@ad<="20040301" and ('thermal' or 'heat') with ('regulating' or 'control') same 'semiconductor' same ('heat sink' or 'heat spreader')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:47
L44	220	@ad<="20040301" and ('thermal' or 'heat') with ('regulating' or 'control') same 'semiconductor device' same ('heat sink' or 'heat spreader')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:47
L45	145	@ad<="20040301" and ('thermal' or 'heat') with ('regulating' or 'control') same 'IC' same ('heat sink' or 'heat spreader')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:48
L46	424	@ad<="20040301" and ('thermal' or 'heat') with ('regulating' or 'control') same 'chip' same ('heat sink' or 'heat spreader')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:48
L47	1508	@ad<="20040301" and (361/695). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:21

L48	144	@ad<="20040301" and (361/696). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:07
L49	1	"6016250".PN.	USPAT; USOCR	OR	ON	2005/10/02 07:07
L50	1	"5773755".PN.	USPAT; USOCR	OR	ON	2005/10/02 07:07
L51	1	"5463529".PN.	USPAT; USOCR	OR	ON	2005/10/02 07:08
L53	181	@ad<="20040301" and ('array' or 'matrix') with 'heat sink' same 'semiconductor device'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:16
L54	24	@ad<="20040301" and 'matrix' with 'heat sink' same 'semiconductor device'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:20
L55	522	@ad<="20040301" and 'matrix' with 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:20
L56	394	@ad<="20040301" and (361/694). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:21
L57	1	"5988488".PN.	USPAT; USOCR	OR	ON	2005/10/02 07:26
L58	1	"5848467".PN.	USPAT; USOCR	OR	ON	2005/10/02 07:26
L59	1162	@ad<="20040301" and (257/718). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:28
L60	952	@ad<="20040301" and (257/717). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:28
L61	711	@ad<="20040301" and (257/718). ccls. and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:28
L62	283	@ad<="20040301" and (257/718). ccls. and 'heat sink' same 'semiconductor'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:29

L63	5	@ad<="20040301" and 'maze' with 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:42
L64	20	@ad<="20040301" and 'helix' with 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:32
L65	35	@ad<="20040301" and 'thermal control' with 'IC'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:42
L66	1	"6016250".PN.	USPAT; USOCR	OR	ON	2005/10/02 07:47